Title (en)

FORGED BERYLLIUM-COPPER BULK MATERIAL

Title (de)

SCHÜTTGUT AUS GESCHMIEDETEM BERYLLIUMKUPFER

Title (fr)

MATÉRIAU EN VRAC EN CUPROBÉRYLLIUM FORGÉ

Publication

EP 2264199 A4 20150708 (EN)

Application

EP 09725472 A 20090225

Priority

- JP 2009053449 W 20090225
- JP 2008087628 A 20080328

Abstract (en)

[origin: EP2264199A1] The present invention provides a forged beryllium-copper bulk material, wherein the hardness of the central portion is 0 to 10% higher than that of the front surface, the Vickers hardness of the central portion is 240 or more, the tensile strength is 800 N/mm 2 or more, and the bulk material having uniformity to such an extent that variation in measured values of the tensile strength in arbitrary directions is within 5%.

IPC 8 full level

C22C 9/00 (2006.01); **C22C 9/06** (2006.01); **C22F 1/00** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP US)

C22C 9/00 (2013.01 - EP US); **C22C 9/06** (2013.01 - EP US); **C22F 1/08** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)

EP 2264199 A1 20101222; **EP 2264199 A4 20150708**; **EP 2264199 B1 20161228**; CN 101981211 A 20110223; CN 101981211 B 20121212; JP 5416091 B2 20140212; JP WO2009119237 A1 20110721; KR 101467617 B1 20141201; KR 20100134619 A 20101223; US 2010329923 A1 20101230; WO 2009119237 A1 20091001

DOCDB simple family (application)

EP 09725472 A 20090225; CN 200980111010 A 20090225; JP 2009053449 W 20090225; JP 2010505469 A 20090225; KR 20107021629 A 20090225; US 88042910 A 20100913